

Electronic Patent Application Fee Transmittal

Application Number:	10644195
Filing Date:	20-Aug-2003
Title of Invention:	METHOD OF FORMING SILICON-CONTAINING INSULATION FILM HAVING LOW DIELECTRIC CONSTANT AND LOW FILM STRESS

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Attorney Docket Number:	ASMJP.137AUS

Filed as Large Entity

Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)

Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1700